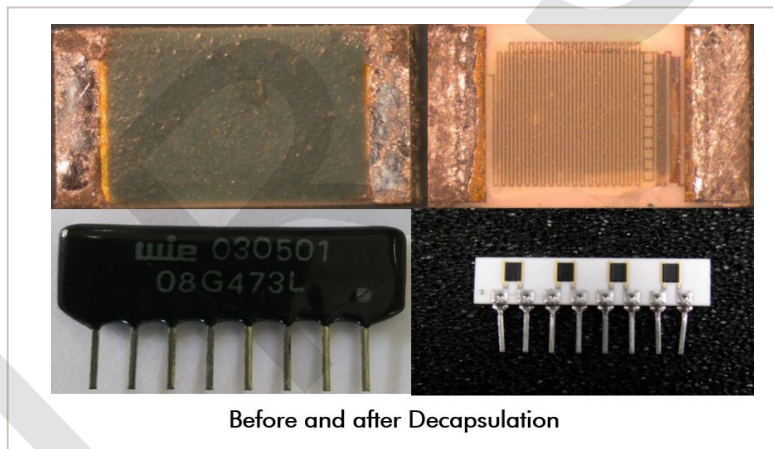


## Chemical Process for Decapsulation of Electronic Components

U R Rao Satellite Centre (URSC) of Indian Space Research Organisation (ISRO) has developed the technology of Chemical Process for Decapsulation of Electronic Components. This decapping mechanism removes the encapsulants without damaging the internal circuitry so that effective failure analysis can be carried out. Innovative chemical process has been developed for decapping of various polymer encapsulated electronic devices without affecting integrity of internal micro structure or interconnects. The principle of this chemical method is polymer swelling mechanism using mixture of organic solvents followed by conversion of encapsulated polymer into filterable smaller fragments.



### Salient Features & Major Specifications

- ✦ Decapsulation of polymer encapsulated devices without affecting the overall integrity of failed components.
- ✦ Import Substitute for decapsulation.
- ✦ Minimum lead time.
- ✦ Low cost and time saving.

## Technology Transfer

URSC-ISRO offers to transfer this technology of Chemical Process for Decapsulation of Electronic Components to industries in India with adequate experience and facilities. Industries interested in obtaining knowhow may write giving details of their present activities, infrastructure and facilities.

Technology Transfer & Industry Coordination Division (TTID),  
Programme Planning and Evaluation Group (PPEG),

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🌐 <https://www.ursc.gov.in/industry/index.jsp>

